

BT169 series

Thyristors logic level

Rev. 5 — 30 September 2011

Product data sheet

1. Product profile

1.1 General description

Passivated, sensitive gate thyristors in a SOT54 plastic package.

1.2 Features and benefits

- Designed to be interfaced directly to microcontrollers, logic integrated circuits and other low power gate trigger circuits.

1.3 Applications

- General purpose switching and phase control applications.

1.4 Quick reference data

- $V_{\text{DRM}}, V_{\text{RRM}} \leq 200 \text{ V}$ (BT169B)
- $V_{\text{DRM}}, V_{\text{RRM}} \leq 400 \text{ V}$ (BT169D)
- $V_{\text{DRM}}, V_{\text{RRM}} \leq 600 \text{ V}$ (BT169G)
- $I_{\text{T(RMS)}} \leq 0.8 \text{ A}$
- $I_{\text{T(AV)}} \leq 0.5 \text{ A}$
- $I_{\text{TSM}} \leq 8 \text{ A}$

2. Pinning information

Table 1. Discrete pinning

Pin	Description	Simplified outline	Symbol
1	anode (a)	SOT54 (TO-92)	sym037
2	gate (g)		
3	cathode (k)		



3. Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
BT169B	-	plastic single-ended leaded (through hole) package; 3 leads	SOT54
BT169D			
BT169G			

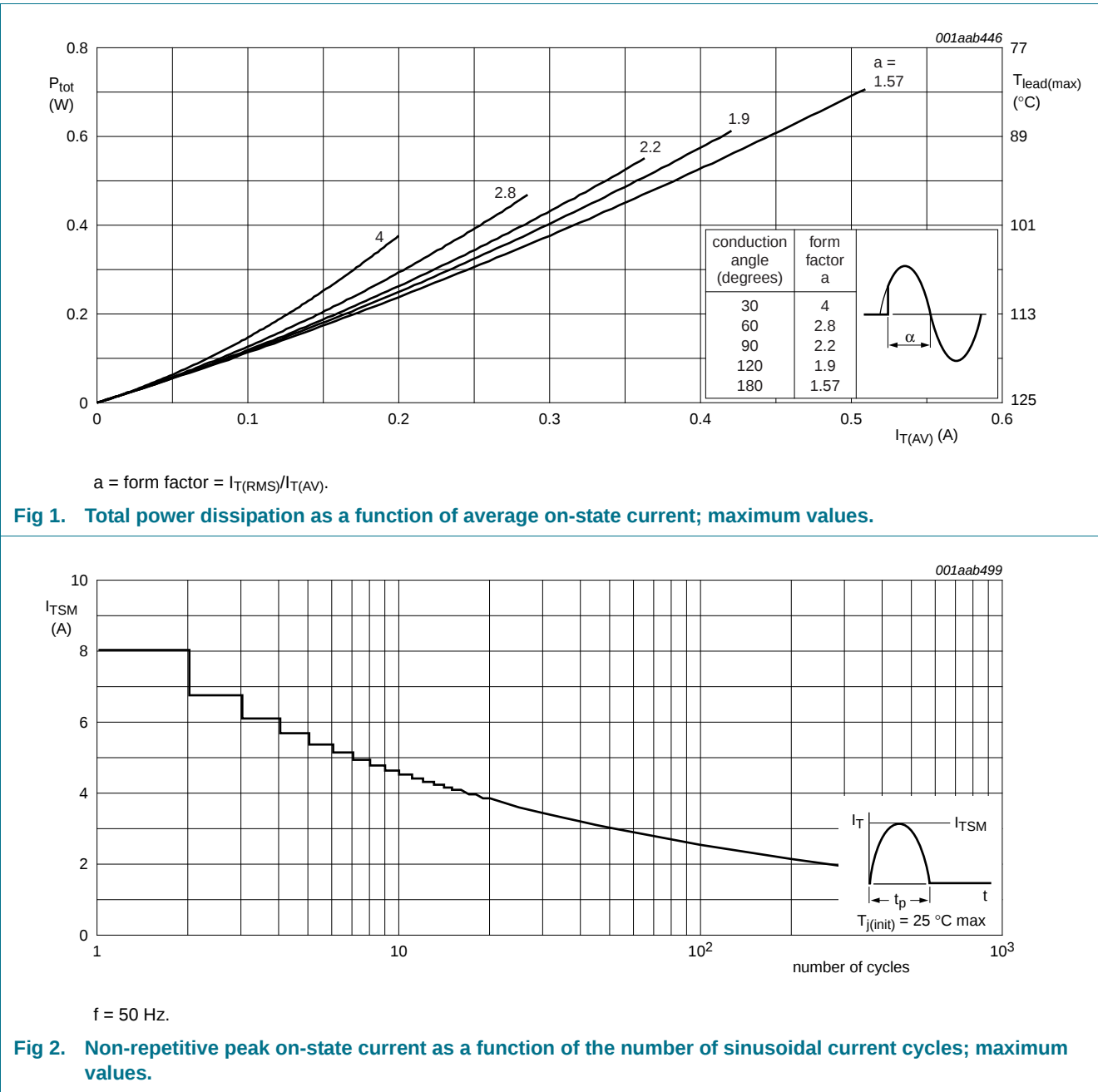
4. Limiting values

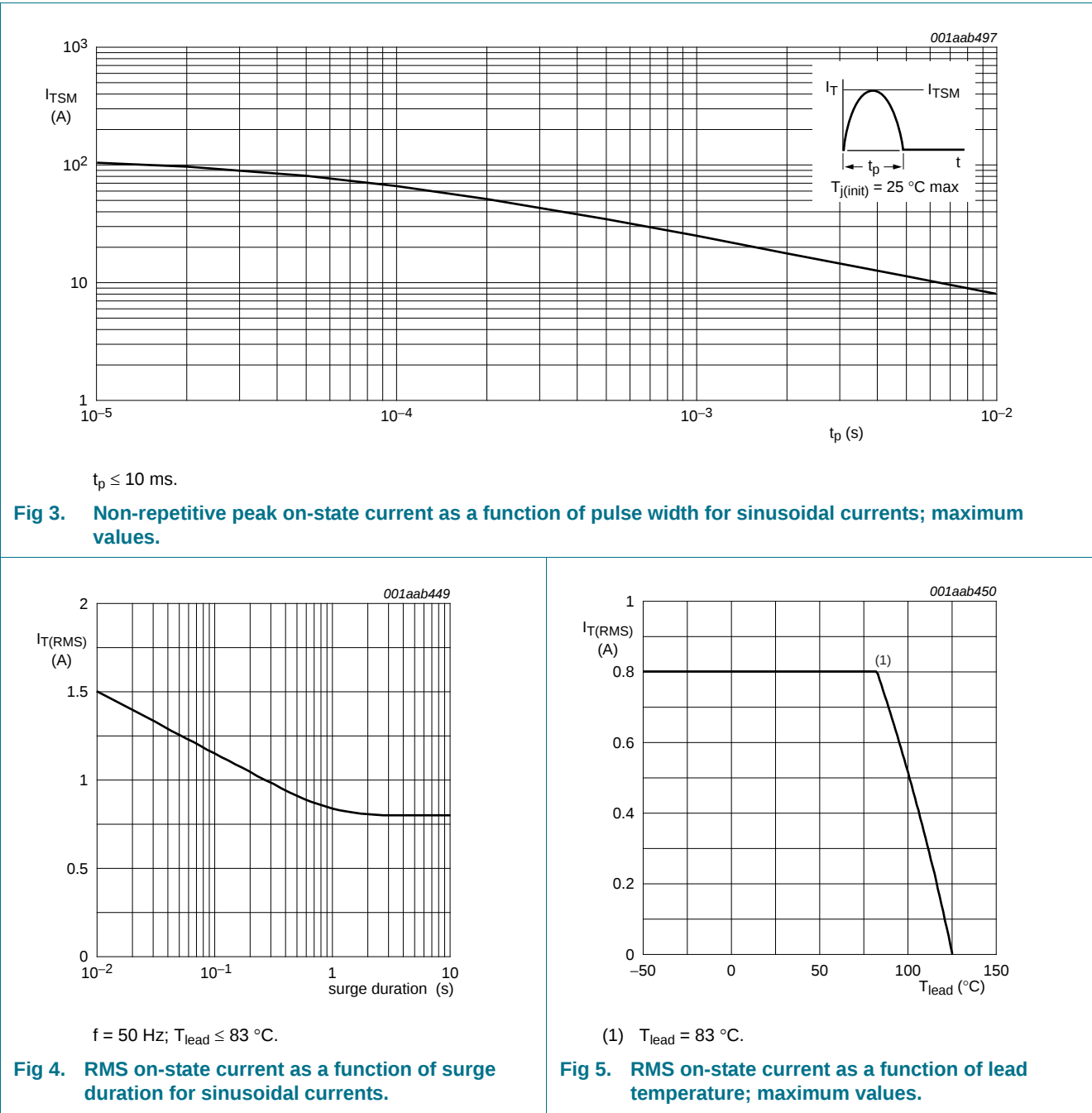
Table 3. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{\text{DRM}}, V_{\text{RRM}}$	repetitive peak off-state voltages				
	BT169B		[1] -	200	V
	BT169D		[1] -	400	V
	BT169G		[1] -	600	V
$I_{\text{T(AV)}}$	average on-state current	half sine wave; $T_{\text{lead}} \leq 83\text{ }^{\circ}\text{C}$; see Figure 1	-	0.5	A
$I_{\text{T(RMS)}}$	RMS on-state current	all conduction angles; see Figure 4 and 5	-	0.8	A
I_{TSM}	non-repetitive peak on-state current	half sine wave; $T_{\text{j}} = 25\text{ }^{\circ}\text{C}$ prior to surge; see Figure 2 and 3			
		$t = 10\text{ ms}$	-	8	A
		$t = 8.3\text{ ms}$	-	9	A
I^2t	I^2t for fusing	$t = 10\text{ ms}$	-	0.32	A^2s
dI_{T}/dt	repetitive rate of rise of on-state current after triggering	$I_{\text{TM}} = 2\text{ A}$; $I_{\text{G}} = 10\text{ mA}$; $dI_{\text{G}}/dt = 100\text{ mA}/\mu\text{s}$	-	50	$\text{A}/\mu\text{s}$
I_{GM}	peak gate current		-	1	A
V_{GM}	peak gate voltage		-	5	V
V_{RGM}	peak reverse gate voltage		-	5	V
P_{GM}	peak gate power		-	2	W
$P_{\text{G(AV)}}$	average gate power	over any 20 ms period	-	0.1	W
T_{stg}	storage temperature		-40	+150	$^{\circ}\text{C}$
T_{j}	junction temperature		-	125	$^{\circ}\text{C}$

- [1] Although not recommended, off-state voltages up to 800 V may be applied without damage, but the thyristor may switch to the on-state. The rate of rise of current should not exceed 15 A/ μs .

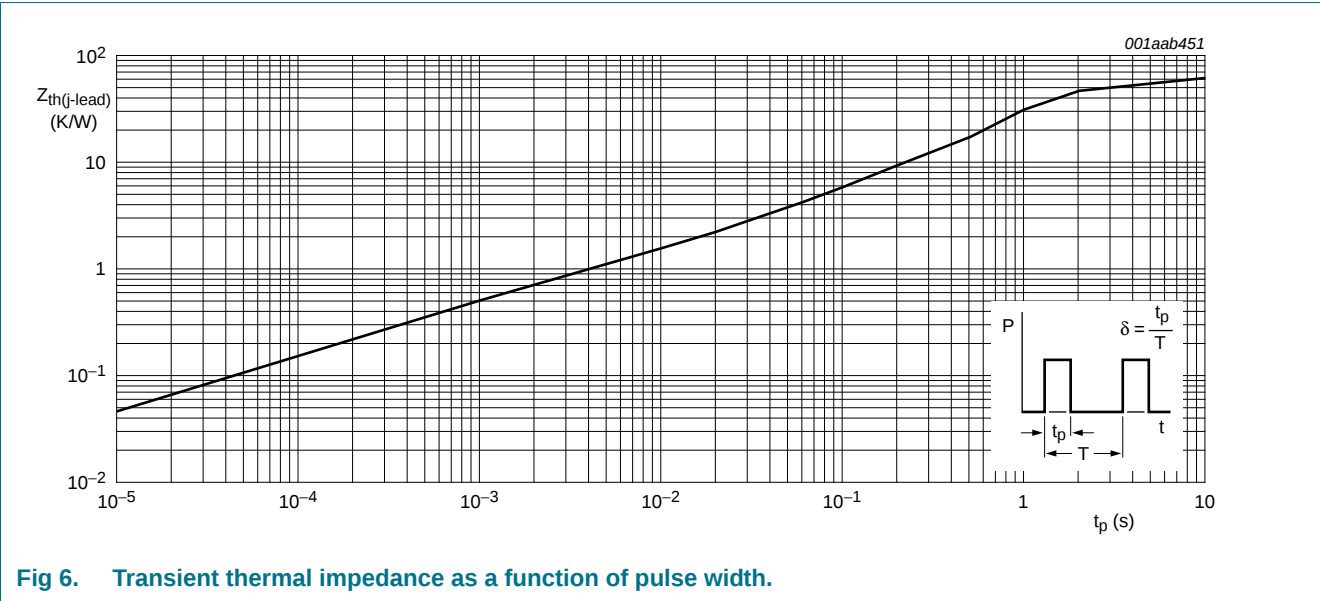




5. Thermal characteristics

Table 4. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-lead)}$	thermal resistance from junction to lead		-	-	60	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	printed-circuit board mounted; lead length = 4 mm	-	150	-	K/W

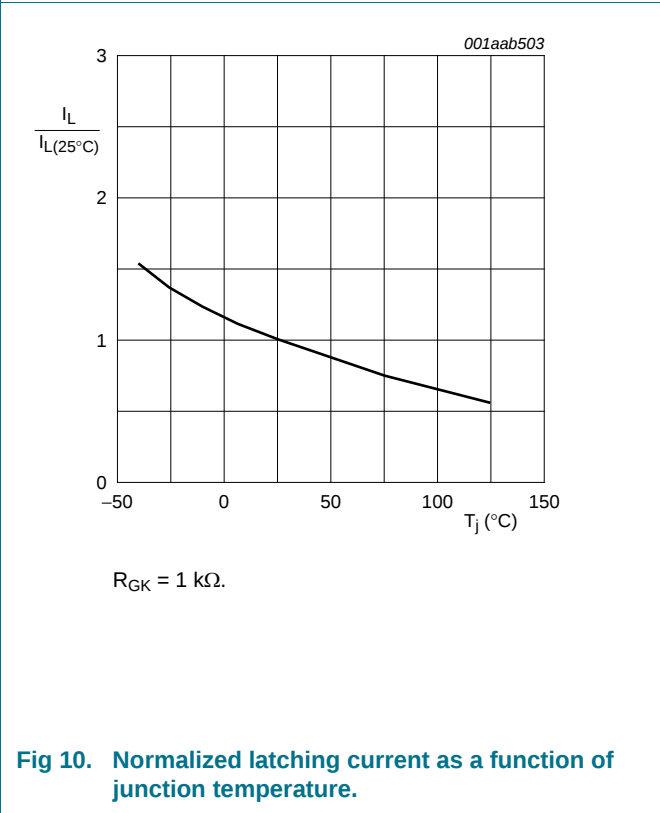
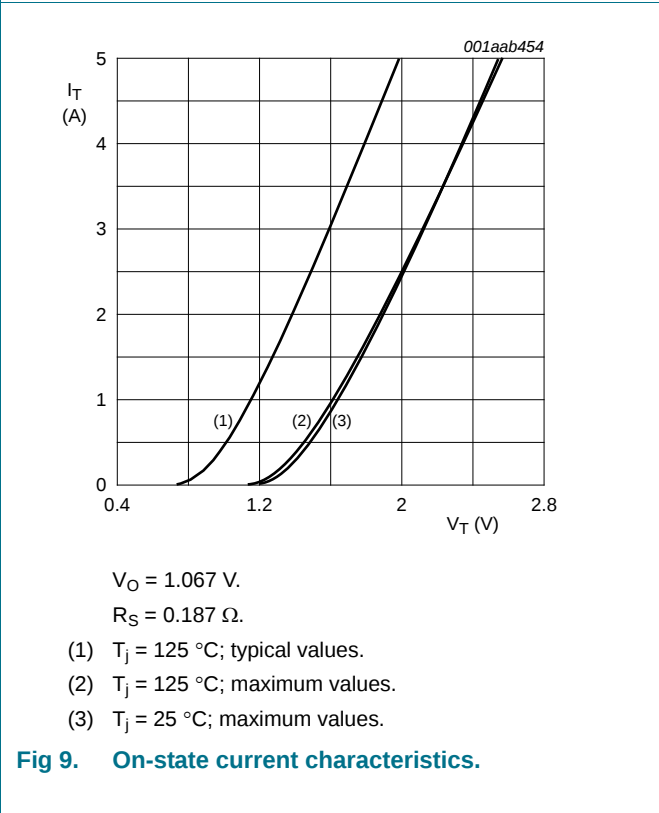
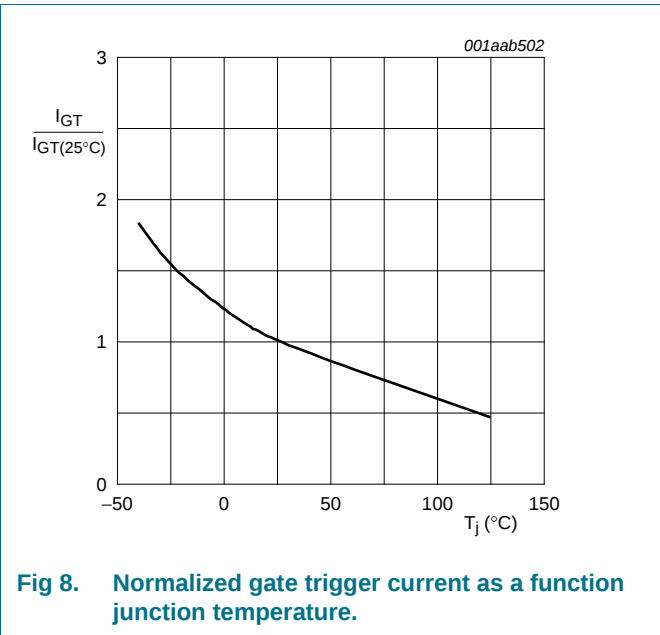
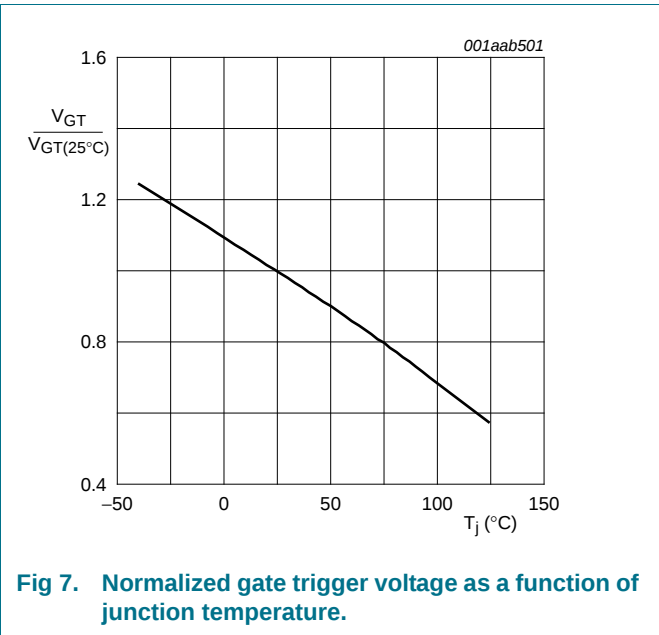


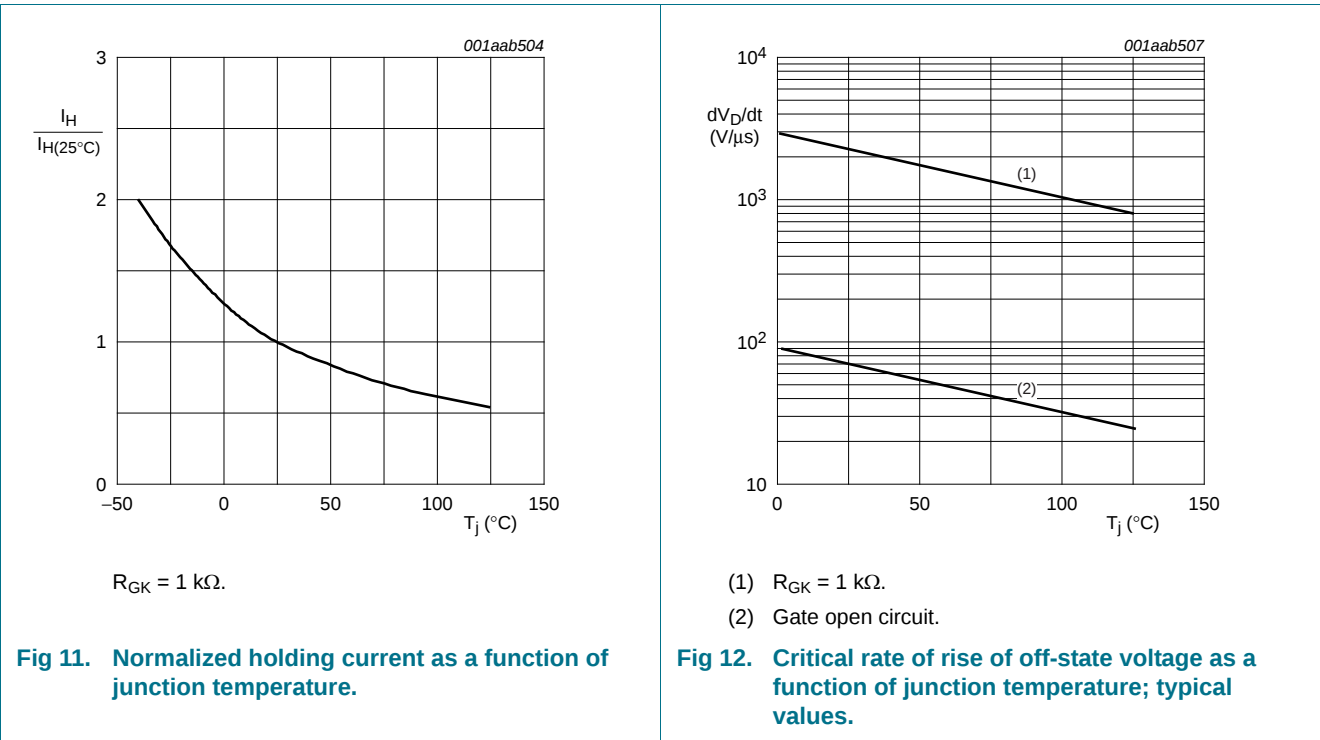
6. Characteristics

Table 5. Characteristics

$T_j = 25\text{ }^{\circ}\text{C}$ unless otherwise stated.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
I_{GT}	gate trigger current	$V_D = 12\text{ V}$; $I_T = 10\text{ mA}$; gate open circuit; see Figure 8	-	50	200	μA
I_L	latching current	$V_D = 12\text{ V}$; $I_{GT} = 0.5\text{ mA}$; $R_{GK} = 1\text{ k}\Omega$; see Figure 10	-	2	6	mA
I_H	holding current	$V_D = 12\text{ V}$; $I_{GT} = 0.5\text{ mA}$; $R_{GK} = 1\text{ k}\Omega$; see Figure 11	-	2	5	mA
V_T	on-state voltage	$I_T = 1.2\text{ A}$	-	1.25	1.7	V
V_{GT}	gate trigger voltage	$I_T = 10\text{ mA}$; gate open circuit; see Figure 7				
		$V_D = 12\text{ V}$	-	0.5	0.8	V
		$V_D = V_{DRM(max)}$; $T_j = 125\text{ }^{\circ}\text{C}$	0.2	0.3	-	V
I_D, I_R	off-state leakage current	$V_D = V_{DRM(max)}$; $V_R = V_{RRM(max)}$; $T_j = 125\text{ }^{\circ}\text{C}$; $R_{GK} = 1\text{ k}\Omega$	-	0.05	0.1	mA
Dynamic characteristics						
dV_D/dt	critical rate of rise of off-state voltage	$V_{DM} = 67\% V_{DRM(max)}$; $T_j = 125\text{ }^{\circ}\text{C}$; exponential waveform; see Figure 12				
		$R_{GK} = 1\text{ k}\Omega$	500	800	-	$\text{V}/\mu\text{s}$
		gate open circuit	-	25	-	$\text{V}/\mu\text{s}$
t_{gt}	gate controlled turn-on time	$I_{TM} = 2\text{ A}$; $V_D = V_{DRM(max)}$; $I_G = 10\text{ mA}$; $dI_G/dt = 0.1\text{ A}/\mu\text{s}$	-	2	-	μs
t_q	circuit commuted turn-off time	$V_D = 67\% V_{DRM(max)}$; $T_j = 125\text{ }^{\circ}\text{C}$; $I_{TM} = 1.6\text{ A}$; $V_R = 35\text{ V}$; $dI_{TM}/dt = 30\text{ A}/\mu\text{s}$; $dV_D/dt = 2\text{ V}/\mu\text{s}$; $R_{GK} = 1\text{ k}\Omega$	-	100	-	μs





7. Package information

Epoxy meets requirements of UL94 V-0 at 1/8 inch.

8. Package outline

Plastic single-ended leaded (through hole) package; 3 leads

SOT54

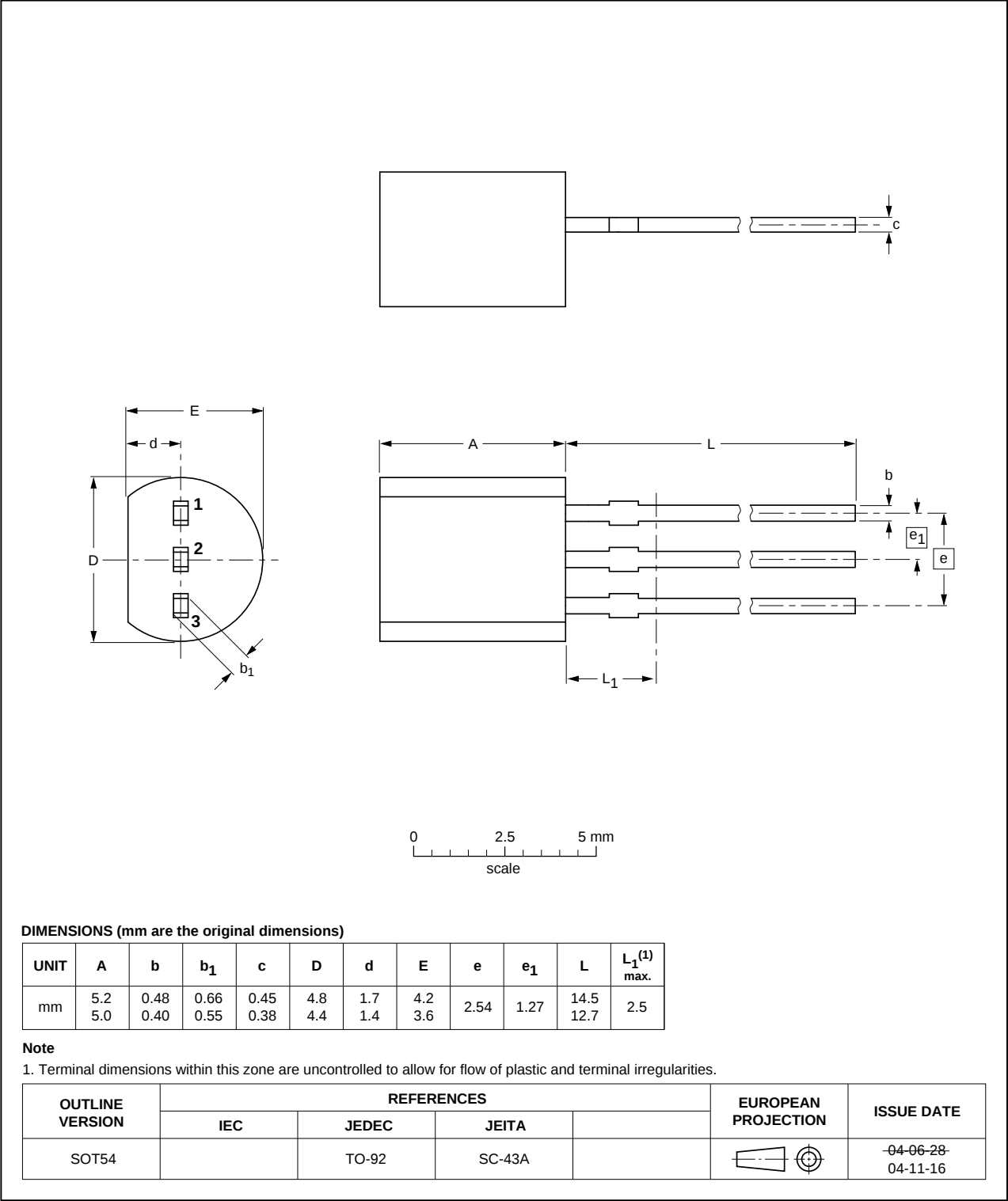


Fig 13. Package outline SOT54 (TO-92).

9. Revision history

Table 6. Revision history

Document ID	Release date	Data sheet status	Change notice	Order number	Supersedes
BT169_SERIES v.5	20110930	Product data sheet	-	9397 750 13512	BT169_SERIES v.4
Modifications:					
- The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. - Legal texts have been adapted to the new company name where appropriate.					
BT169_SERIES v.4	20040823	Product data sheet	-	9397 750 13512	BT169_SERIES v.3
Modifications:					
- The format of this data sheet has been redesigned to comply with the new presentation and information standard of Philips Semiconductors. - Section 1.4 "Quick reference data": BT169E obsolete, removed from list. - Table 2 "Ordering information": BT169E obsolete, removed from table. - Table 3 "Limiting values": BT169E obsolete, removed from table.					
BT169_SERIES v.3	20010902	Product specification	-	not applicable	BT169_SERIES v.2
BT169_SERIES v.2	20010901	Product specification	-	not applicable	BT169_SERIES v.1
BT169_SERIES v.1	19970901	Product specification	-	not applicable	-

10. Legal information

10.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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